	Material Comp © Copyright 2005. I S INDUSTRIES® international and Par	PC, Bannockb	urn, Illinois. A	All rights reserved untions.	nder both	This docume level parts, t	ent is a declaration	ation of a the second s	of the substances mpasses all lowe	within th r level m	e manufactur aterials for w	rer listed i hich the n	tem. Note: i nanufacture	if the item is an as r has engineering	sembly with lowe responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type Distribute	Form Type * Declaration Cl Distribute Class 6 - RoHS				ass * S Yes/No, Homogeneous Materials and Mfg Information						
Supplier	r Information															
Company	name*	Company unique ID				Unique ID Authority					Response Date*					
onsemi												2025-05-11				
Contact N	ame	Title - Contact				Phone - Contact*					Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	d Representative*		Title - Representative				Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item   FCPF400		Number Mfr Item Name				Effective Date Version Manufacturing S   2025-05-11 CNP		uring Site	Weight*       2107.333		UOM	Unit Type			
			)N80Z	I80Z     SF2 800V 400mOhm E TO220F								mg	Each			
/Ianufa	cturing Proccess Informa	tion					•	A								
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		J-STD-020 MSI	L Rating	Peak Proc		ss Body Temperature Ma		Time at Peak	Temperat	ture Numb	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed			CU Alloy NA				0 C 30			seconds 3						
omments	6															
or more	information regarding material	composition	please refer to	o page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	13.5	mg	Supplier	Silicon (Si)	7440-21-3		13.5	mg
Die Attach	4.013	mg	Supplier	Silver (Ag)	7440-22-4		0.0602	mg
			А	Lead (Pb)	7439-92-1	7a	3.7522	mg
			Supplier	Tin (Sn)	7440-31-5		0.2007	mg
lead Frame	1289.5	mg	Supplier	Silver (Ag)	7440-22-4		2.579	mg
			Supplier	Iron (Fe)	7439-89-6		1.2895	mg
			Supplier	Copper (Cu)	7440-50-8		1285.2446	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3868	mg
Mold Compound	785.0	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		23.55	mg
			Supplier	Proprietary	Proprietary Data		11.775	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		39.25	mg
			Supplier	Carbon Black (C)	1333-86-4		3.925	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		117.75	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		39.25	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		549.5	mg
Plating	13.2	mg	Supplier	Tin (Sn)	7440-31-5		13.2	mg
Wire Bond - Al	2.12	mg	Supplier	Aluminum (Al)	7429-90-5		2.12	mg